

RELIABILITY MONITOR REPORT  
FOR

**uSOP Package**

**Dallas Semiconductor**

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Dallas, TX 75244-3292

This Report was prepared by  
Dallas Semiconductor Reliability Engineering

**Summary:**

The data in the tables that follow was generated as the result of an on-going Package Reliability Monitor. The assemblies covered by this package monitor are:

ASSY SITE	PINS	PACKAGE		
ATP (Amkor, PI)	10	uSOP	ATP (Amkor, PI)	8 uSOP
Carsem	10	uSOP	Carsem	8 uSOP
NSEB	10	uSOP	NSEB	8 uSOP

The calculated failure rate for this assembly is:

**FAILURE RATE:**                      **MTTF (YRS): 19623**                      **FITS: 5.8**

The parameters used to calculate this failure rate are as follows:

**Cf: 60%**                      **Ea: 0.7**                      **B: 0**                      **Tu: 25 °C**                      **Vu: 5.5 Volts**

The reliability data follows. At the start of this data is a description of the assembly vehicle used to generate this reliability data. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available. This report covers data between 7/1/03 and 6/30/04 .

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**Assembly Information:**

Package Type:                      uSOP 3mm  
Flammability:                      UL 94-V0  
Moisture Sensitivity                      Level 1  
(JEDEC J-STD20A)  
Date Code Range:                      0327      to      0416

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**OPERATING LIFE**

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	FA NO
HIGH VOLTAGE LIFE	0327	DS3905	125C, 5.5 VOLTS	1000 HRS	45	0	
HIGH TEMP OP LIFE	0401	DS4510	125C, 5.5 VOLTS	1000 HRS	45	0	
HIGH TEMP OP LIFE	0416	DS3902	125C, 5.5 VOLTS	1000 HRS	77	0	
				<b>Total:</b>		<b>0</b>	

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